

semiconductor packaging news

We search for industry news, so you don't need to.

2026 Media Guide

semiconductor packaging news

News Focused on Semiconductor Packaging

Global Silicon Wafer Shipments to Rebound 5.4% in 2025

Global silicon wafer shipments will rise 5.4% in 2025 to 12,824 million square inches, SEMI reported, driven by AI-fueled demand for advanced wafers. Growth will continue through 2028, reaching a record 15,485 MSI as AI computing expands from data centers to the edge.

SEMI

Tough Engineering Changes? Where Can You Turn?

Engineering changes are a reality that need to be dealt with. Do you have qualified rework technicians to do the job efficiently and reliably?

Circuit Technology Center

Jensen Huang says Nvidia's AI chips are now being manufactured in Arizona. Nvidia CEO Jensen Huang said its Blackwell AI chips are now fully produced and assembled in Arizona after Trump urged U.S. manufacturing. At GTC, Nvidia also unveiled a \$1B Nokia partnership for 5G/6G tech and new quantum computing projects to bolster U.S. innovation.

CNBC

Multi-Sensor Metrology for the most challenging Advanced Packaging Applications. Users want to measure various applications on one tool rather than several tools to get the required results. Ultra-precise, non-contact measuring techniques work for a multitude of packaging applications.

Technical Paper

Discover consistency for your operations

Explore the reliable solutions for jet dispensing, conformal coating, plasma treatment, and selective soldering from Nordson.

Nordson Electronics Solutions

NVIDIA May Be TSMC's Only A16 Customer So Far While Apple Reportedly Yet to Start Talks

NVIDIA marked the first U.S.-made Blackwell wafer at TSMC's fab, signaling deeper ties as it becomes the sole customer testing TSMC's A16 node for 2027. The move marks AI's first lead in adopting TSMC's top process, though rising A16 costs could pressure NVIDIA's margins.

TrendForce

Technical Papers

- Novel Molded FCBGA Package Platform For Highly Reliable Automotive Applications
- Eliminating Interfacial Delamination in High-Power Automotive Devices
- RAIG Minimizes Corrosion, Allows Higher Gold on ENEPIG
- A Universal AI-Powered Segmentation Model for PCBA & Semiconductor
- Peer viewpoint: semiconductor innovation for telecommunication networks
- Current Characterization of Various Cu RDL Designs In Wafer Level Packages (WLP)
- Peer viewpoint: AI data centers are driving a semiconductor revolution

MORE TECH PAPERS

Fusion and Hybrid Bonding Experts

EVC's industry-leading process solutions, expertise and HI Competence Center accelerate the development and implementation of heterogeneous integration technology.

EV Group

Shanghai's IC Industry in High Gear, Up 11.3% in the First Three Quarters of 2025. Shanghai's GDP rose 5.5% year-on-year to CNY 4.07 trillion in the first three quarters of 2025, driven by strong growth in integrated circuits, biomedicine, and AI. IC output surged 11.3%, fueled by robust policies, investment funds, and a thriving tech ecosystem of 1,200+ firms.

TrendForce

Intel Reportedly Eyes Retired TSMC Veteran Wei-Jen Lo, Advanced Node Pioneer, to Lead R&D

Intel is reportedly courting retired TSMC veteran Wei-Jen Lo, a key figure behind TSMC's 2nm and EUV breakthroughs, to lead its R&D push in the sub-2nm race. The move, if confirmed, could shake Taiwan's chip sector as Intel expands its foundry business with U.S. backing.

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Analysis Of Multi-Chiplet Package Designs and Requirements

This white paper discusses the rising complexity of multi-die semiconductor packages, challenges in testing interconnected chips, and how standards like UCIE simplify production testing workflows.

Amkor Technology

Ultra-Thin Wafer Handling

Brewer Science temporary wafer bonding systems allow for safe handling and transport of ultrathin wafers during rigorous backside processing steps.

Brewer Science

Sponsor



Today's Sponsor



brewer science

Sponsor



Die-Module Attach (Pastes & Films)

Die-Attach Adhesives with low moisture absorption for MSL Level-1 applications for reliability. Outstanding thermal conductivity with low moisture absorption- stress-free bonding.

AI Technology, Inc.

Test Your Knowledge

Which of the following was not invented by Thomas Edison? Light Bulb, Movie Projector, Telegraph or Phonograph.

See answer below.

Sponsor



EZ-FLO High Precision Dispense Tips

Each needle is machined from solid stainless steel as opposed to rolled tubing. The resulting smoother internal profile enhances material flow and consistency. Learn more.

DL Technology

Industry Press

Koh Young Unveils Breakthrough

Innovations at Productronica and SEMICON Europa 2025

Koh Young will showcase a wave of innovations at Productronica and SEMICON Europa 2025, taking place November 18-21 at Messe München, Germany. Visitors can explore ...

Koh Young

ElevATE Expands Global Presence with New Office in Hsinchu, Taiwan

Semiconductor is excited to announce the opening of its first office in Hsinchu, Taiwan. The new location will strengthen support for customers and partners across Asia ...

ElevATE Semiconductor

STMicroelectronics' integrated GaN flyback converters simplify design and silence audible noise

STMicroelectronics is introducing a series of GaN flyback converters that simplify designing and building compact, efficient USB-PD chargers, fast battery chargers, and auxiliary ...

STMicroelectronics

Ruselectric Highlights System Control

Upgrades for Critical Power Equipment. Ruselectric highlights its system control upgrades for critical power equipment for enhanced reliability, operational control, and ease-of-maintenance. These upgrades are ...

Ruselectric

MORE INDUSTRY PRESS

"Build Up" I/C Packages --

USA Fabrication High layer counts. Low CTE material sets. 20um Dielectrics /12um Traces - ITR Approved - 50um "Stay Flat" Cores. Learn more.

Advanced Component Labs, Inc.

Sponsor



Quote of the Day

- 30,000+ daily e-mail subscribers
- 125,000 unique visitors past 12 months
- Readership from 130 countries
- #1 newsletter and website for industry professionals

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Why Advertise With Semiconductor Packaging News?

Digital media continues to expand as industry professionals seek daily updates on news and events shaping the semiconductor packaging and micro-electronics market. An advertising campaign in Semiconductor Packaging News provides excellent visibility with high-frequency advertising designed to meet every budget. We reach 125,000 industry professionals who are eager to learn more about your products and services.

A digital advertising campaign features:

- Advertising campaigns in the daily newsletter & website
- Banner ads for branding (160 x 300 pixels vertical)
- Text ads intrigue readers to click to your web pages to learn more
- Technical papers provide lead generation for your sales channel
- Corporate news releases published at no cost
- Calendar to post your shows, webcasts and important events
- Custom e-mail broadcast to subscribers dedicated to your company

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Analytical Data

Analytical data collected from independent firms confirm our readership continues to expand. Semiconductor Packaging News e-mail newsletter is broadcast to over 30,000 subscribers every business day.



During the past 12 months Semiconductor Packaging News has reached over 125,000 unique visitors from 130 countries. The e-mail newsletter subscriber base is always up-to-date and is managed by an independent e-mail company.

Top 10 markets by geographic readership:

- | | |
|-----------------|------------------|
| ▪ North America | ▪ China |
| ▪ Japan | ▪ Germany |
| ▪ South Korea | ▪ Netherlands |
| ▪ Taiwan | ▪ United Kingdom |
| ▪ Singapore | ▪ France |

Demographics by region of the world:
43% Americas, 35% Asia Pacific, and 22% Europe

Industry organizations such as SEMI, IMAPS, MEPTEC and IEEE partner with Semiconductor Packaging News to reach their members and drive visitors to their events and trade shows.

Comments from several Semiconductor Packaging News advertisers:

"SPN provides a great opportunity to reach a range of prospects on a daily basis for a very competitive price. We can advertise for an entire year for the cost of a small booth at a local show."
J.B.

"The White Paper program in SPN has delivered hundreds of prospects from around the world. This is a great way to reach new customers."
R.H.

"We are very pleased with the exposure and support from our ad campaign in SPN."
D.P.

"Semiconductor Packaging allows us to reach our markets around the globe. We book new orders from readers of SPN."
J.F.

"In this period of decline in print publications, our customers are turning to the web as the source of information. We have benefited from our aggressive use of SPN as an advertising vehicle."
R.B.

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Semiconductor Packaging News Readers

2026

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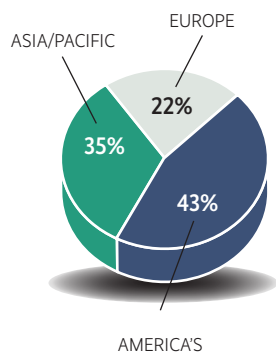
Over 30,000 daily subscribers find Semiconductor Packaging News to be their go-to source for news and information in the semiconductor and micro-electronics assembly market. Semiconductor Packaging News subscribers and website visitors are the industry professionals you want to reach; they are your prospects and your customers.

Rather than waiting for an issue of a trade publication every month or two, our daily e-mail broadcast reaches professionals that have a need to know – and who bear the responsibility for looking ahead to keep their companies on top! They keep themselves up to speed by reading Semiconductor Packaging News daily. Over 500,000 articles have been clicked and read by Semiconductor Packaging News readers.

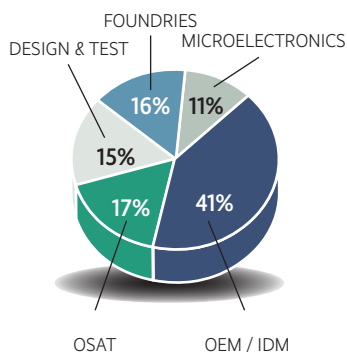


Based on a readership survey we are proud to share data and commentary from industry professionals who took part in our survey.

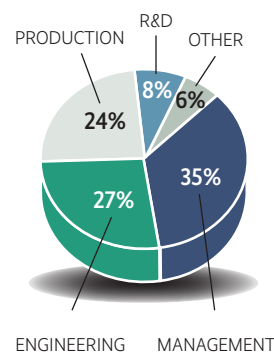
Readership Breakdown



Company Type



Job Description



Comments from several Semiconductor Packaging News subscribers:

"Semiconductor Packaging News is the only daily newsletter focused on the packaging side of the industry."

"SPN is the best daily newsletter, I look forward to reading each day."

"This is the best daily newsletter for insight on the micro-electronics and semiconductor industries."

"I read SPN regularly and find the mix of information to be quite interesting."

"As an Asia Pacific reader, I find your newsletter useful to gain the global perspective on the growing 3D packaging."

"All the important news in one place, great way to start my morning."

"Nice Job. Really stands out. Very newswy with lots of good stuff."

A photograph of three business professionals. In the foreground, a woman with blonde hair, wearing a dark pinstripe suit jacket over a white collared shirt, is smiling broadly. Behind her to the right, a man with grey hair, wearing a dark suit, white shirt, and patterned tie, is also smiling. To the left of the woman, another person is partially visible but out of focus. The background is a bright, blurred office environment. A large, dark blue geometric shape, resembling a stylized 'A' or a triangle, is overlaid on the left side of the image.

2026

Media Guide

Monthly Media Reports

Banner Ads

Text Ads

Top Sponsor Position

Technical Papers generate leads each month

Custom E-mail Broadcast

Did You Know: Text ads will typically deliver 2-3 times as many clicks as a banner ad. Advertisers use banner ads to build the company brand and text ads to intrigue readers to click on their ads and drive readers to pages on their website.

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Media Report

EV Group

2025 ADI Performance

PBB: On Circuitry | C1 Great Insight | SPW Semiconductor Packaging News Numbers in the monthly columns are click costs across each ad. Click the image link to preview the ad.

Ad No.	Title	Type	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
9393	Ev Group Logo	SPN Logo												
13119	Fusion and Hybrid Bonding Experts	SPN Text												
13119	Nest-Gon Fusion and Hybrid Bonding	SPN Banner												
12553	3D Layer Release Technology for 3D Packaging and Logic Scaling	SPN Text												
Totals														

Your Available Ads

Click your ads to check the keywords.

Text Ad No. 13553 Active SPN

3D Layer Release Technology for 3D Packaging and Logic Scaling
Ultra-thin layer transfer from silicon carriers with nanometer precision using an H laser and ion-gate release layers enables 3D packaging & logic scaling.
EV Group

Text Ad No. 13186 Active SPN

Fusion and Hybrid Bonding Experts
EV's industry-leading process solutions, expertise and Hi-Compliance Center accelerate the development and implementation of heterogeneous integration technology.
EV Group

Text Ad No. 12368 Inactive

Heterogeneous Exposure for Adv Packaging
This paper examines how multilayer exposure technology overcomes limitations of traditional lithography in back-end processing, providing unsurpassed flexibility, scalability and cost benefits.
EV Group

Text Ad No. 10251 Inactive

Accelerating 3D IC packaging roadmap
EV Group EVG's multi-seen Structures HTS bond aligner with sub-50 nm wafer-to-wafer alignment accuracy, available in its industry benchmark GENPDS D3 HTS bond aligner system.
EV Group

Text Ad No. 9056 Inactive

Solutions for 3D Chip Stacking in High Volume Manufacturing
Fusion and hybrid wafer bonding enabling leading-edge 3D stacked CPUs, memory stacking and 3D SoC devices. Learn EV Group

Text Ad No. 9181 Inactive

Mask Alignment Speed & Accuracy
New 12-aligner HT Automated Mask Alignment System from EV Group enables throughput and alignment accuracy and produces up to 30 percent lower cost of ownership.
EV Group

Text Ad No. 9130 Inactive

Sponsor Logo No. 9393 Active SPN

Banner No. 11199

Active SPN

Banner No. 8131

Inactive

Banner No. 10116

Inactive

Banner No. 13052

Inactive

Banner No. 8437

Inactive

Banner No. 10116

Inactive

Banner No. 10272

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Banner No. 8156

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Banner No. 10116

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IV Group

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Amkor Technology

SK Hynix, a critical Nvidia supplier, has already sold out chips for 2026 as AI demand booms
SK Hynix reported record quarterly revenue and profit, driven by soaring demand for its high-bandwidth memory used in AI chips. The company plans to expand capacity by 2026, with next-generation HBM4 chips launching soon and supply already sold out.

CNBC

Ultra-Thin Wafer Handling

Brewer Science temporary wafer bonding systems allow for safe handling and transport of ultrathin wafers during rigorous backside processing steps.

Brewer Science

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brewer science

Sponsor

Die-Module Attach (Pasters & Films)

Die Attach Adhesives with low moisture absorption for MSL Level-1 applications for reliability. Outstanding thermal conductivity with low moisture absorption - stress-free bonding.

AI Technology, Inc.

Test Your Knowledge
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Sponsor

EZ-FLO High Precision Dispense Tips

Each needle is machined from solid stainless steel as opposed to rolled tubing. The resulting smoother internal profile enhances material flow and consistency. Learn more.

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Koh Young

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ElevATE Semiconductor

STMicroelectronics' Integrated GaN Byback Converters Simplify Design and Silence Audible Noise
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STMicroelectronics

Ruselectric Highlights System Control Upgrades for Critical Power Equipment
Ruselectric highlights its system control upgrades for critical power equipment for enhanced reliability, operational control, and ease-of-maintenance. These upgrades are ...

Ruselectric

MORE INDUSTRY PRESS

"Build Up" 1/C Packages -- USA Fabrication
High layer counts, Low CTE material sets, 20µm Dielectrics /12µm Traces - IATF Approved - Shown "Day Flat" Core. Learn more.

Advanced Component Labs, Inc.

Quote of the Day
"With the possible exception of the equator, everything begins somewhere."

Peter Fleming

Number 1 in bond testers
Sigma is the best bond tester the market has to offer. It comes with game-changing automation capabilities for operator-free loading, testing, and analyzing. Learn more.

xyztec

What Year Was It?
John Glenn Returns to Space
Nearly four decades after he became the first American to orbit the Earth, Senator John Herschel Glenn, Jr., is launched into space again as a payload specialist aboard the space shuttle Discovery. See the answer below.

Cartoon of the Day

Sponsor Text Ad

Sponsor Logo

Premium Position

Text Ad

Text Ad

Silver Campaign

The Silver Campaign includes 8 days per month in the e-mail newsletter and website. Ads will usually run twice per week in this campaign.

3-month campaign \$1,200/month
6-month campaign \$1,100/month
12-month campaign \$1000/month

Silver-Plus Campaign

The Silver-Plus Campaign includes 10 days per month in the e-mail newsletter and website plus a premium ad position each month.

3-month campaign \$1,500/month
6-month campaign \$1,450/month
12-month campaign \$1,350/month

Gold Campaign

The Gold Campaign includes 15 days per month in the e-mail newsletter and website including a top sponsor position with company logo each month plus a premium position each month.

3-month campaign \$2,000/month
6-month campaign \$1900/month
12-month campaign \$1800/month

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About Us

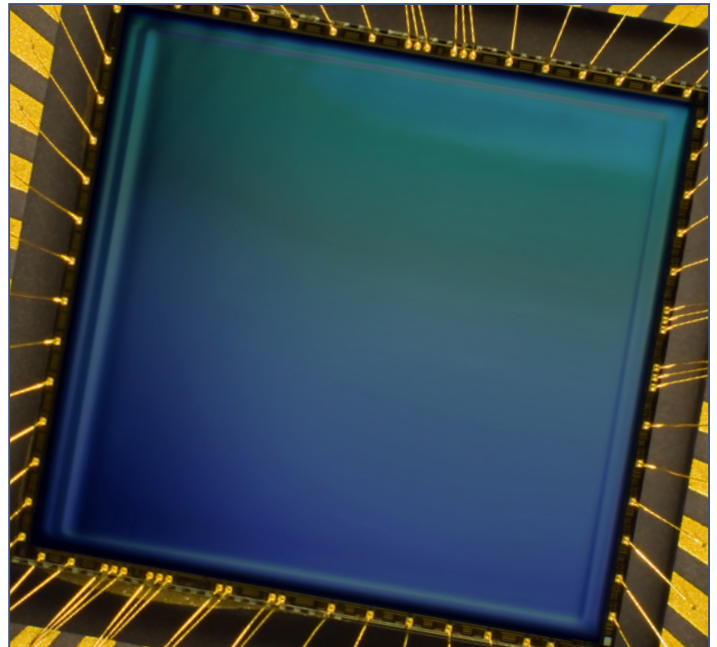
2026 Media Guide

We believe it's our job to dig through the unending stream of news, articles, features, and discussions to deliver information, covering the world of semiconductor packaging and micro electronics, to our readers. Every night we scour the news from over 100 sources to find the best industry news articles. We package this information into a convenient newsletter that is delivered to our subscribers e-mail every business day.

The Semiconductor Packaging Newsletter and website features links to industry and technology news stories and feature articles about the semiconductor packaging market. We publish the latest corporate and product news announcements industry companies submit to us.

Thousands of technical papers are downloaded every month and we'll publish your technical paper at no cost. You'll also find commentaries, cartoons, an industry event calendar and much more.

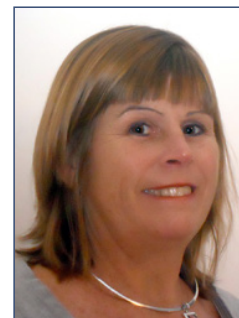
We look forward to working with you on your digital sponsorship campaign.



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